## Ladder Assembly Procedure



Belle II - New Collaborators Meeting

## Introduction

- Overview of the assembly procedure for a Layer 6 ladder.
- Drawings and slides without HEPHY header are taken from Y. Onuki's talk, presented at the $14^{\text {th }}$ B2GM in March 2013
- Procedure recently tested @ IPMU
- Pictures from test assembly and new ideas added
- Modification of some jigs and steps is in progress


## Ladder Assembly - Organization

- Sharing of production:
- L3: Melbourne - 7 + spares (2 sensors each)
- L4: Tata (at IPMU) - $10+$ spares (3 sensors each)
- L5: HEPHYVienna - 12 + spares (4 sensors each)
- L6: Tokyo (IPMU) - 16 + spares ( 5 sensors each)
- Contract between Tata and IPMU is being prepared
- Interest of Italian groups (ex-SuperB) to join ladder assembly


## Ladder 6 with Origami Readout



- Challenging procedure, several jigs needed for assembly
- Master drawings \& jigs prepared by Y.Onuki


## SVD ladder assembly flow



## Common Proc.01: Placing DSSD stopper



Common Proc.02: Placing DSSD


## Common Proc.03: Removing DSSD stopper



Common Proc.04: Aligning PA1 and PA2. Dispensing glue.


## Common Proc.05: Gluing PA1 and PA2



Common Proc.06: Wire bonding after removing PA1 and PA2-jig


Mechanical QA: Visual inspection of bonding wires.

Common Proc.07: Assembly bench w/ FW\&BW mount bracket


Calibrate coordinate system according to ladder mount position

Common Proc.08: Placing DSSD(-z)


## Common Proc.09: Placing DSSD(CE)



Repeating Common Proc.01-6

Common Proc.10: Placing DSSD(+z)


## Common Proc.11: Removing Alignment-jig



## Common Proc.12: Replacing FW part.





FW jig very close to sensor $\rightarrow$ damage of edge possible Should be done before Common Proc. 08!

In this procedure, only replacing FW part.
The other jigs never move.

## Common Proc.13: Placing FW DSSD and FW hybrid board



## Common Proc.14: Replacing BW part



BW jig very close to sensor $\rightarrow$ damage of edge possible Should be done before Common Proc. 08!

Common Proc.15: Placing BW DSSD and BW hybrid board


## Common Proc.16: Placing XYZӨ-stage. Aligning DSSD(BW).



The detail of this procedure can be seen in the slide of Shimizu at Wetzlar

## Common Proc.17:Placing XYZӨ-stage. Aligning DSSD(-z).



The detail of this procedure can be seen in the slide of Shimizu at Wetzlar

## Common Proc.18:Placing XYZӨ-stage. Aligning DSSD(CE).



The detail of this procedure can be seen in the slide of Shimizu at Wetzlar

Common Proc.19:Placing XYZӨ-stage. Aligning DSSD(+z).


The detail of this procedure can be seen in the slide of Shimizu at Wetzlar

## Common Proc.20:Placing XYZӨ-stage. Aligning DSSD(FW).



## Common Proc.21: Removing XYZӨ-stage



## Mechanical QA:

Inspection of alignment of DSSDs w/ the coordinate measuring machine. The detail of the procedure can be seen in the slide of Shimizu at Wetzlar http://indico.mppmu.mpg.de/indico/materialDisplay.py?contribld=37\&sessionld=5\&materialld=slides\&confld=2114

## Independent BW and FW part assembly

- Baseline procedure
- Full ladder is assembled at one site
- Sensors can be aligned before hybrids are attached.
- Independent assembly of BW, FW and Origami parts
- Origami assembly unchanged
- Pre-assembled FW and BW modules has to be attached
- Can we alignment complete BW and FW modules?
- Xy $\theta$-stage needs to be modified in order to align sensor + hybrid at once
- The following assembly procedures of BW and FW modules have to be modified, too


## SVD ladder assembly flow



FW\&BWProc.01: Aligning PF2 and PB2


FW\&BWProc. 02 : Placing PF2-jig and PB2-jig. Vacuum chucking.
 PF(B)2.

FW\&BWProc.03: Picking up the jigs. Dispensing glue.


FW\&BWProc. 04 : Placing again and gluing PF2 and PB2


FW\&BWProc.05: Removing PB2-jig and PF2-jig


FW\&BWProc.06: Lifting up the assembly-bench


FW\&BWProc.07: Wire bonding after picked up the F(B)W parts.


After the screwing the hybrid board, We can plug the connector.

Mechanical QA: Visual inspection of bonding wires Electrical QA: Readout test with APVDAQ

FW\&BWProc.08: Lifting up the assembly-bench


FW\&BWProc. 09 : Returning the FW and BW part.


FW\&BWProc.10: Placing PF2-jig and PB2-jig again.


Not tested yet!

FW\&BWProc.11: Picking up the BW and FW parts.


FW\&BWProc.12: Placing PF1 and PB1. Dispensing glue on them.


FW\&BWProc.13: Gluing PF1 and PB1.


FW\&BWProc.14: Removing the jigs


FW\&BWProc.15: Placing PF2-jig and PB2-jig again.


FW\&BWProc.16: Picking up the parts. Wire-bonding.


FW\&BWProc.17: Returning the PF2,PB2-jigs


FW\&BWProc.18: Placing Slant-jig and Backward-jig.


FW\&BWProc.19: Picking up the slant hybrid board.


Picking up hybrid board with thin wire.

FW\&BWProc.20: Moving the X-stages


Moving the X -stage to the edge of hybrid board


FW\&BWProc.21: Clamping the edge of hybridboard


FW\&BWProc.22: Picking up the Slant-jig and Backward-jig.


FW\&BWProc.23:


Place jigs at a secure location -

## SVD ladder assembly flow



Gluing ribs Proc.01: Placing the FW and BW parts


Gluing ribs Proc.02: Placing the bridge and screwing


Gluing ribs Proc.03: Placing the supports


Gluing ribs Proc. 04 : Placing the ribs


Gluing ribs Proc.05: Placing the stopper pins


Gluing ribs Proc.06: Moving the boards to the position.


Moving the hybrid boards to the proper positions.

Gluing ribs Proc.07: Dispensing glue on the ribs


Gluing ribs Proc. 08 : Placing the Slant-jig and Backward-jig


Gluing ribs Proc.09: Gluing and connecting the board on the MB.


The jigs will stop at the proper Z position.


Gluing ribs Proc.10: Picking up the Slant-jig and Bacward-jig


## Placing Slant and BW parts

- Precision of pins poor
- Original Idea:
- Angle of slanted sensor is defined by slant jig, 2 pins and linear bushings
- Not precise enough
- Fragile setup
- Possible solution:
- Use two wedge shaped jigs to determine angle
- Allows to use high precision pins
- Needs to be verified

Gluing ribs Proc.11:


## SVD ladder assembly flow



OrigamiProc.01: Preparing the Assembly-bench


OrigamiProc.02: Placing the dummy FW and BW DSSD


Dummy DSSDs are just used for making flat $Z$ surface.

## OrigamiProc.03: Preparing the AIREX-jig



OrigamiProc.04: Placing the AIREX stopper


## OrigamiProc.05: Placing the AIREX



OrigamiProc.06: Removing AIREX stopper. Dispensing glue


OrigamiProc.07: Gluing AIREX


## OrigamiProc.08: Removing AIREX-jig



Dummy BW-DSSD is not glued with the AIREX

## OrigamiProc.09: Preparing the Origami-alignment-jig



## OrigamiProc.10: Placing Origami(CE). Wire-binding APV25



Origami(CE) can be aligned by alignment holes


Mechanical QA: Visual inspection of bonding wires Electrical QA: Readout test with APVDAQ

OrigamiProc.11: Placing Origami(CE)-jig.


OrigamiProc.12: Dispensing glue.


## OrigamiProc.13: Gluing Origami(CE)



## OrigamiProc.14: Removing Origami(CE)-jig



## OrigamiProc.15: Preparing the Origami-alignment-jig



OrigamiProc.16: Placing Origami(-z). Wire-binding APV25


Alignment hole


Mechanical QA: Visual inspection of bonding wires Electrical QA: Readout test with APVVDAQMu)

OrigamiProc.17: Placing Origami(-z)-jig


## OrigamiProc.18: Dispensing glue



OrigamiProc.19: Gluing Origami(-z)


OrigamiProc.20: Gluing Origami(-z)


OrigamiProc.21: Placing Airex(+z)


## OrigamiProc.22: Preparing the Origami-alignment-jig



OrigamiProc.23: Placing Origami(+z). Wire-binding APV25


Origami(+z) can be aligned with the alignment holes

Mechanical QA: Visual inspection of bonding wires Electricalal QA: Readout test with APVDAQ

OrigamiProc. 24 : Placing Origami(+z)-jig


## OrigamiProc.25: Dispensing glue



For slant AIREX
For Origami(+z) AIREX

OrigamiProc. 26 : Gluing Origami(+z)


OrigamiProc.27: Removing Origami(+z)-jig.DSSD wire-bond


Mechanical QA: Visual inspection of bonding wires Electrical QA: Readout test with APVDAQ

OrigamiProc.28: Wrapping PAs


Wrapping and gluing as usual way.

## SVD ladder assembly flow



Final Proc.01: Preparing the Origami part

Final Proc.02: Lifting up the assembly-bench


Final Proc. 03 : Dispensing the glue on the BW dummy DSSD


Final Proc. 04 : Placing down the assembly-bench


Final Proc. 05 : Lifting up again. Glues are stamped on BW.


Final Proc.06: Replacing the Ribs+FW+BW parts. Dispensing glue.


Final Proc.07: Placing the Assembly-bench


Final Proc.08: Gluing the Origami and Ribs.


Final Proc.09: Placing down the bench. Dispensing glue.


Dispensing glue some spots on the backside of Origami(+z)

Final Proc.10: Gluing the Origami(+z)


Final Proc.11: Attaching the rods at the rib support.


The rods act like a bumper and handles.

Final Proc.12: Pulling up the support with rods.


Final Proc. 13 : Finish.


Mechanical QA:

- Inspection of alignment of DSSDs w/ the coordinate machine.
- Thermal cycle test(not all, sampling)

Electrical QA:

- Readout test with APVDAQ
- Source test

- The ladder is still mounted on the rib jig
- Cooling pipe already attached


## Thank you



